

Product / Process Change Notification



N° 2018-060-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of New Lead Frame Material for TSLP-6 Package

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **14th September 2018**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Chairman of the Supervisory Board: Dr. Eckart Süner
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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► **Products affected:** Please refer to 1_cip18060_a.xlsx

► **Detailed Change Information:**

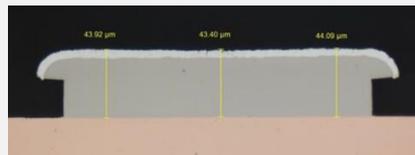
Subject: Introduction of new leadframe material for TSLP-6 package

Reason: To further ensure our product supply

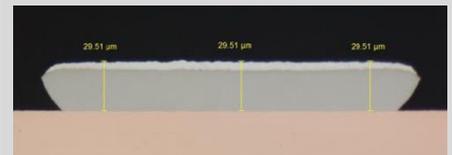
Description: Old New

■ Leadframe bump shape

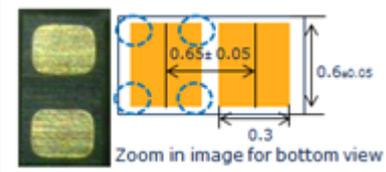
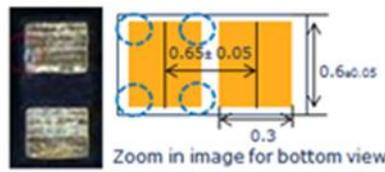
Mushroom



Tapered



■ Footprint



■ Remarks

Sharp pad radius

Round shape pad radius

The new pad shape is due to the new leadframe design

Reflow Soldering and Package dimension remain **UNCHANGED**

Lead pitching remain **UNCHANGED**

► **Product Identification:** Internal traceability ensured via Baunumber, Lot number & date code

► **Impact of Change:**

Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No change in fit and form (except round shape pad radius)

Products with new pad design are fully compatible on board at customers end.

Reflow Soldering and Package dimension remain **UNCHANGED**

Lead pitching remain **UNCHANGED**

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► Attachments:

1_cip18060_a.xlsx	Affected product list
2_cip18060_a.pdf	Final qualification report

► Time Schedule:

■ Final qualification report:	available
■ First samples available:	available
■ Intended start of delivery:	15.10.2018 onwards, or earlier based on customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

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Introduction of New Lead Frame Material for TSLP-6 Package



Sales name	SP number	OPN	Package
BGA 725L6 E6327	SP000942752	BGA725L6E6327FTSA1	PG-TSLP-6
BGS 12PL6 E6327	SP001003644	BGS12PL6E6327XTSA1	PG-TSLP-6